



DMP3160L

P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	Rds(on)	I _D T _A = +25°C
2017	122mΩ @ V _{GS} = -10V	-2.7A
-30V	190mΩ @ V_{GS} = -4.5V	-2.0A

Description

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- DC-DC Converters
- Power Management Functions

Features

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMP3160LQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

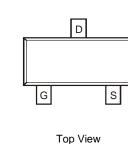
https://www.diodes.com/quality/product-definitions/

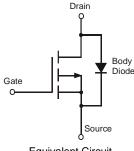
Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (c3)
- Terminal Connections: See Diagram
- Weight: 0.008 grams (Approximate)

SOT23

Top View





Equivalent Circuit

Ordering Information (Note 4)

Part Number	Compliance	Case	Packaging
DMP3160L-7	Standard	SOT23	3000/Tape & Reel
DMP3160LQ-7	Automotive	SOT23	3000/Tape & Reel

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information

PS3	ΜY

 $\begin{array}{l} \mathsf{PS3} = \mathsf{Product} \ \mathsf{Type} \ \mathsf{Marking} \ \mathsf{Code} \\ \mathsf{YM} = \mathsf{Date} \ \mathsf{Code} \ \mathsf{Marking} \\ \mathsf{Y} \ \mathsf{or} \ \overline{\mathsf{Y}} = \mathsf{Year} \ (\mathsf{ex:} \ \mathsf{H} = 2020) \\ \mathsf{M} = \mathsf{Month} \ (\mathsf{ex:} \ 9 = \mathsf{September}) \end{array}$

Date Code Key

Year	2007		2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	U		Н	I	J	K	L	М	Ν	0	Р	R
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Character		Symbol	Value	Unit	
Drain-Source Voltage			V _{DSS}	-30	V
Gate-Source Voltage			V _{GSS}	±20	V
Drain Current (Note 5) V _{GS} = -10V	Steady State	T _A = +25°C T _A = +70°C	lD	-2.7 -2	A
Pulsed Drain Current (Note 6)			Ідм	-8	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	PD	1.08	W
Thermal Resistance, Junction to Ambient $@T_A = +25^{\circ}C$ (Note 5)	Reja	115	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

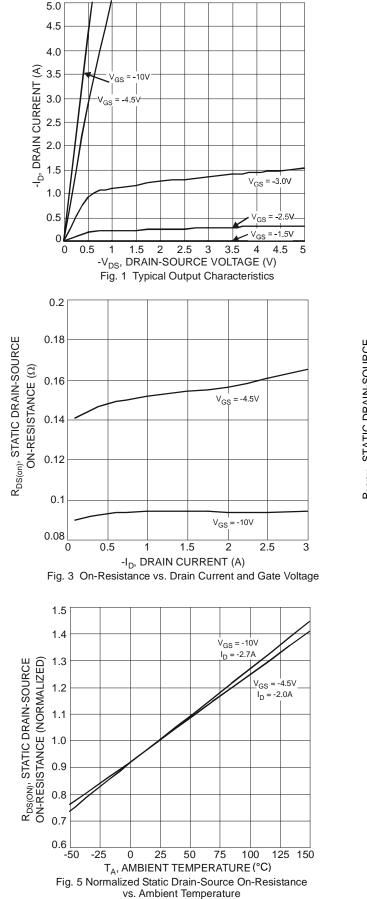
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)				•	•	
Drain-Source Breakdown Voltage	BVDSS	-30	_		V	Vgs = 0V, Ip = -250µA
Zero Gate Voltage Drain Current	IDSS	_	_	-800	nA	Vds = -30V, Vgs = 0V
Gate-Source Leakage	lgss		_	±80 ±800	nA	$V_{GS} = \pm 12V, V_{DS} = 0V$ $V_{GS} = \pm 15V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	VGS(TH)	-1.3	-1.8	-2.1	V	$V_{DS} = V_{GS}, I_D = -250 \mu A$
Static Drain-Source On-Resistance	Page 1		97	122	mΩ	$V_{GS} = -10V, I_D = -2.7A$
	Rds(on)		165	190	11122	$V_{GS} = -4.5V, I_D = -2.0A$
Forward Transfer Admittance	Y _{fs}		5.9	_	S	V _{DS} = -5V, I _D = -2.7A
Diode Forward Voltage (Note 7)	Vsd	_	—	-1.26	V	Vgs = 0V, Is = -2.7A
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	Ciss	_	384.4	—	pF	
Output Capacitance	Coss	_	59.4	_	pF	$V_{DS} = -10V, V_{GS} = 0V$ f = 1.0MHz
Reverse Transfer Capacitance	Crss	_	52.8	_	pF	1 - 1.00012
Gate Resistance	R _G	_	17.1	_	Ω	$V_{GS} = 0V, V_{DS} = 0V,$ f = 1.0MHz
Total Gate Charge (V _{GS} = -4.5V)	Qg	_	4.0		nC	
Total Gate Charge (V _{GS} = -10V)	Qg	_	8.2	_	nC	Vgs = -10V/-4.5V,
Gate-Source Charge	Qgs	_	0.9		nC	$V_{DS} = -15V, I_D = -3A$
Gate-Drain Charge	Q _{gd}	_	1.2	_	nC	
Turn-On Delay Time	t _{D(ON)}	_	4.8		ns	
Turn-On Rise Time	t _R		7.3		ns	V _{DS} = -15V, V _{GS} = -10V,
Turn-Off Delay Time	tD(OFF)		22.5		ns	$R_G = 6\Omega, I_D = -1A$
Turn-Off Fall Time	tF		13.4	_	ns	

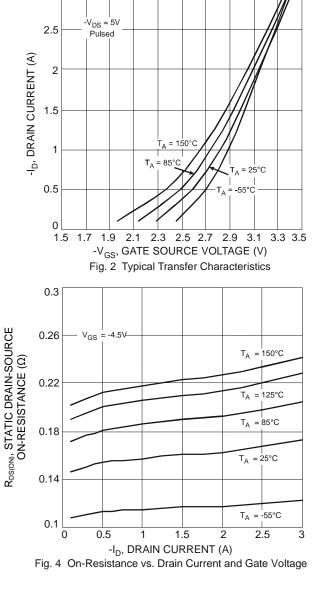
Notes: 5. Device mounted on FR-4 PCB. t \leq 10 sec.

6. Pulse width $\leq 10\mu$ S, Duty Cycle $\leq 1\%$.

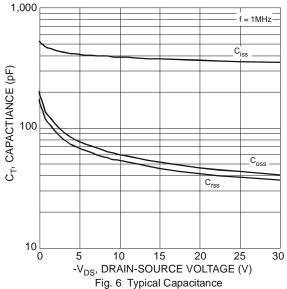
Short duration pulse test used to minimize self-heating effect.
Guaranteed by design. Not subject to product testing.



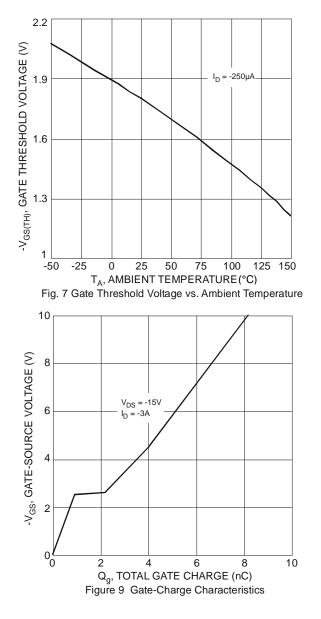


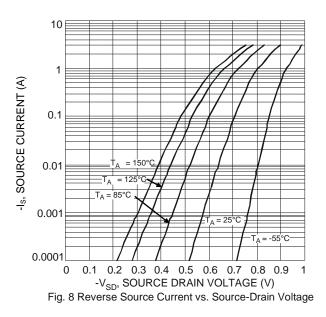


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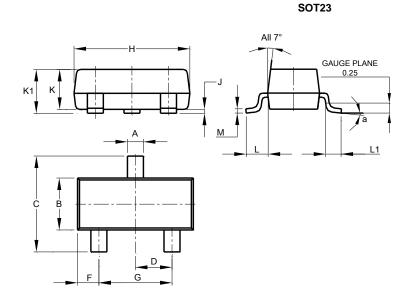






Package Outline Dimensions

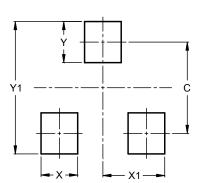
Please see http://www.diodes.com/package-outlines.html for the latest version.



SOT23 Dim Min Max Тур Α 0.37 0.51 0.40 В 1.20 1.40 1.30 2.40 С 2.30 2.50 D 0.89 1.03 0.915 F 0.45 0.60 0.535 G 1.78 2.05 1.83 Н 2.80 3.00 2.90 J 0.013 0.10 0.05 Κ 0.890 1.00 0.975 K1 0.903 1.10 1.025 L 0.45 0.61 0.55 L1 0.25 0.40 0.55 Μ 0.085 0.150 0.110 а 0° 8° --All Dimensions in mm

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



SOT23

Dimensions	Value (in mm)
С	2.0
Х	0.8
X1	1.35
Y	0.9
Y1	2.9



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